

100% Material Declaration Data Sheet FGG676 Package for Spartan-6 FPGAs

Average Weight: 2.981g

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Silicon Die					0.090946	3.051
	Silicon	7440-21-3	100.00		0.090946	
Die Attach Material					0.016016	0.537
	Silver	7440-22-4	77.50		0.012412	
	Bismaleimide Monomer	Trade Secret	15.00		0.002402	
	Acrylate Monomer	Trade Secret	7.50		0.001201	
Mold Compound					1.371554	46.010
	Solid Epoxy Resin	Trade Secret	11.00		0.150871	
	Phenol Resin	Trade Secret	11.00		0.150871	
	Fused Silica	60676-86-0	62.40		0.855850	
	Metal Hydroxide	Trade Secret	15.05		0.206419	
	Carbon Black	1333-86-4	0.55		0.007544	
Gold Wire					0.015517	0.521
	Gold	7440-57-5	99.05		0.015369	
	Palladium	7440-05-3	0.95		0.000147	
	Calcium	7440-70-2	0.00		0.000000	
Solder Balls					0.564707	18.944
	Tin	7440-31-5	96.50		0.544942	
	Silver	7440-22-4	3.00		0.016941	
	Copper	7440-50-8	0.50		0.002824	
Substrate					0.922260	30.938
	Copper	7440-50-8	33.29		0.307002	
	Nickel	7440-02-0	4.84		0.044637	
	Gold	7440-57-5	0.35		0.003228	
	Fiberglass	65997-17-3	17.24		0.158998	
	Non-Halogen FR	NA	0.01		0.000111	
	BT (Core)	NA	36.13		0.333213	
	Solder Mask	NA	8.14		0.075072	

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
09/28/10	1.0	Initial Xilinx release.

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